2SD2504

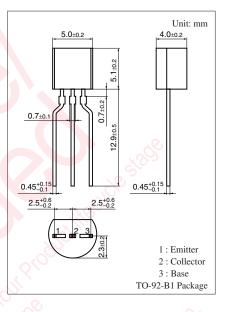
Silicon NPN epitaxial planar type

For low-frequency power amplification

Features

- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$
- \bullet Large collector current I_{C}

Absolute Maximum Ratings $T_a = 25^{\circ}C$							
Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V _{CBO}	15	v				
Collector-emitter voltage (Base open)	V _{CEO}	10	V				
Emitter-base voltage (Collector open)	V _{EBO}	10	V				
Collector current	I _C	5	Α				
Peak collector current *	I _{CP}	9	Α				
Collector power dissipation	P _C	750	mW				
Junction temperature	Tj	150	°C				
Storage temperature	T _{stg}	-55 to +150	°C				



Note) *: $t = 380 \, \mu s$

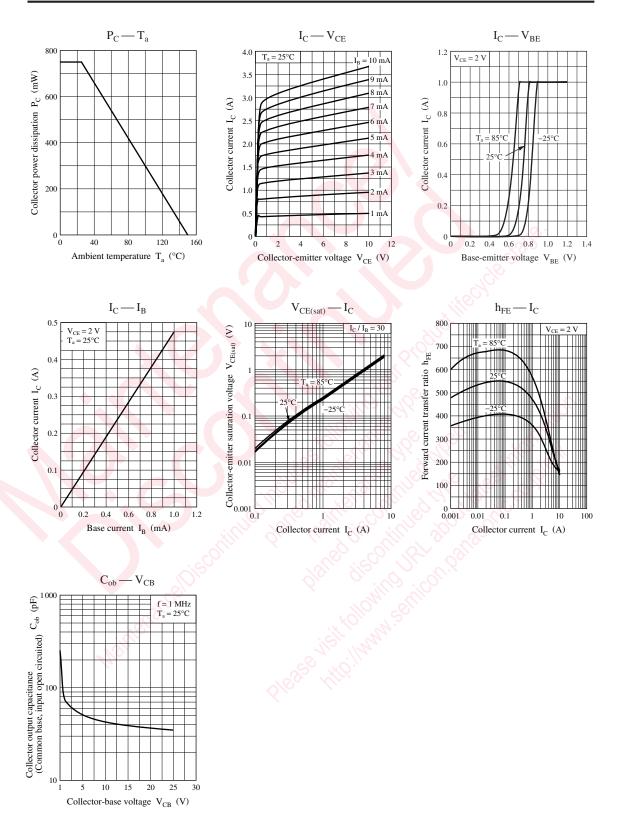
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 1 \text{ mA}, I_{\rm E} = 0$	10	0		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 10 \ \mu A, I_{\rm B} = 0$	10			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 5 V, I_B = 0$			1.0	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 5 V, I_E = 0$			0.1	μΑ
Forward current transfer ratio *	h _{FE1}	$V_{CE} = 2 V, I_C = 0.5 A$	300		800	
	h _{FE2}	$V_{CE} = 2 V, I_C = 2 A$	195			
Collector-emitter saturation voltage *	V _{CE(sat)}	$I_{\rm C} = 3$ A, $I_{\rm B} = 0.1$ A		0.28	0.50	V
Transition frequency	f _T	$V_{CB} = 6 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		170		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		45	65	pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Pulse measurement

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